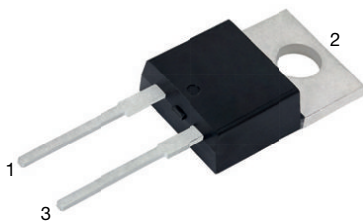
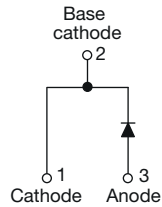


Hyperfast Rectifier, 8 A FRED Pt[®]



TO-220AC 2L



FEATURES

- Hyperfast recovery time, extremely low Q_{rr}
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC[®]-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
V_R	600 V
V_F at I_F	1.5 V
t_{rr} (typ.)	14 ns
T_J max.	175 °C
Package	TO-220AC 2L
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current in DC	$I_{F(AV)}$	$T_C = 142\text{ °C}$	8	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$	80	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\ \mu\text{A}$	600	-	-	V
		$I_F = 8\text{ A}$	-	2.5	3.4	
Forward voltage	V_F	$I_F = 8\text{ A}, T_J = 150\text{ °C}$	-	1.5	2.0	μA
		$V_R = V_R$ rated	-	0.02	30	
Reverse leakage current	I_R	$T_J = 150\text{ °C}, V_R = V_R$ rated	-	21	150	
Junction capacitance	C_T	$V_R = 600\text{ V}$	-	6	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t _{rr}	I _F = 1 A, dI _F /dt = 100 A/μs, V _R = 30 V	-	14	18	ns	
		I _F = 8 A, dI _F /dt = 100 A/μs, V _R = 30 V	-	15	24		
		T _J = 25 °C	-	17	-		
		T _J = 125 °C	-	33	-		
Peak recovery current	I _{RRM}	T _J = 25 °C	-	2.6	-	A	
		T _J = 125 °C	-	4.3	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C	-	22	-	nC	
		T _J = 125 °C	-	77	-		
Reverse recovery time	t _{rr}	T _J = 125 °C	I _F = 8 A, dI _F /dt = 200 A/μs, V _R = 390 V	-	26	-	ns
Peak recovery current	I _{RRM}			-	11	-	A
Reverse recovery charge	Q _{rr}			-	150	-	nC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C
Thermal resistance, junction-to-case	R _{thJC}		-	2.0	2.6	°C/W
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70	
Typical thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2	-	g
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC 2L	ETX0806			

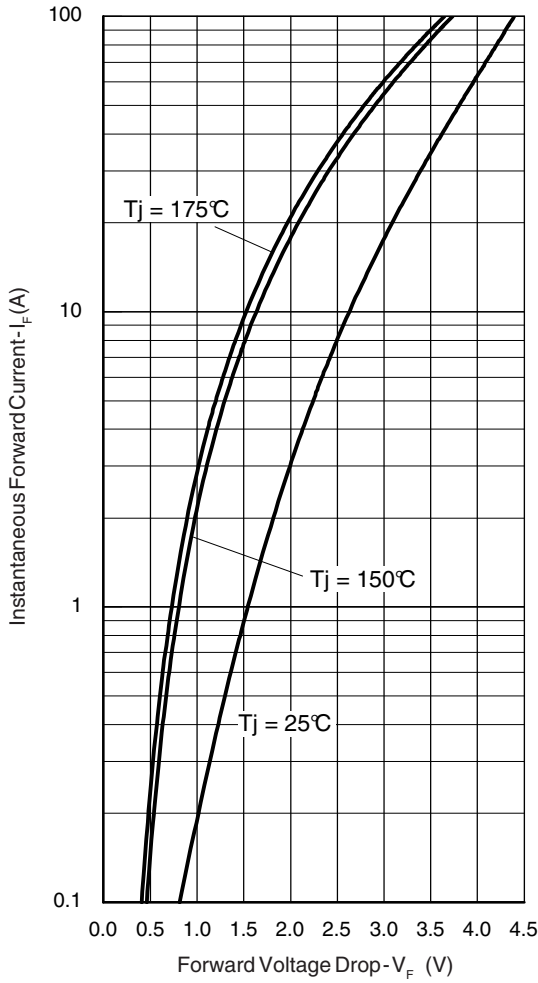


Fig. 1 - Typical Forward Voltage Drop Characteristics

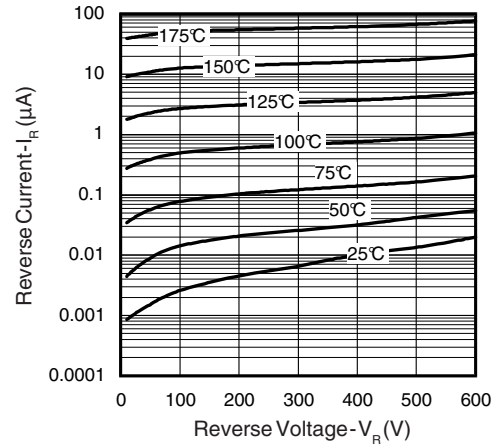


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

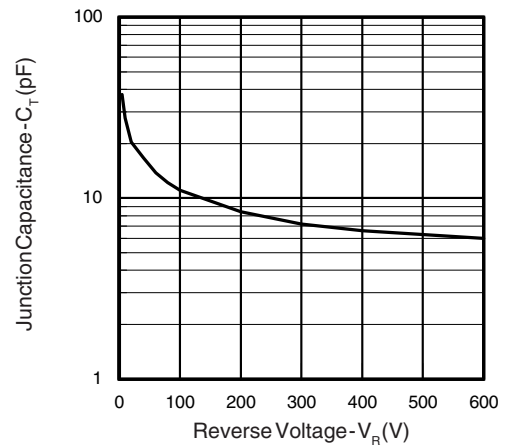


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

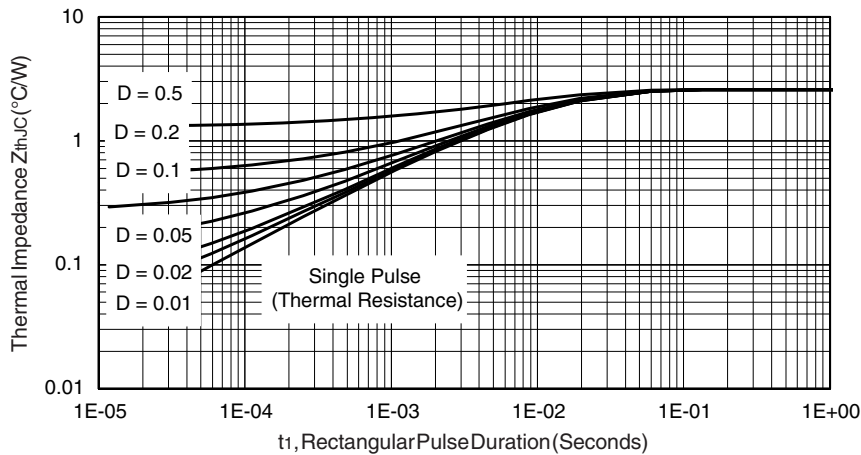


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

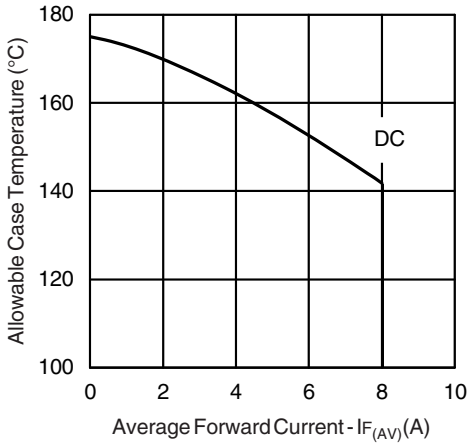


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

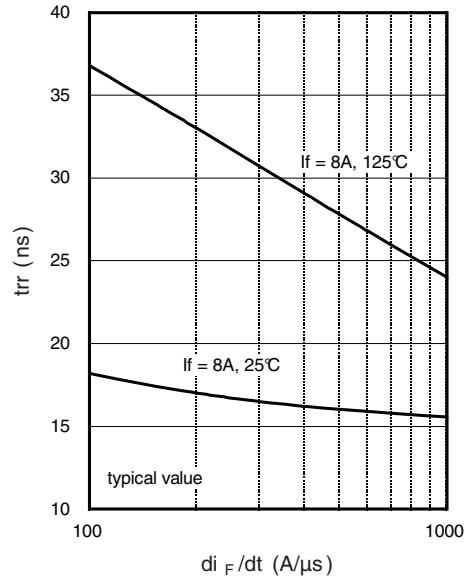


Fig. 7 - Typical Reverse Recovery vs. di_F/dt

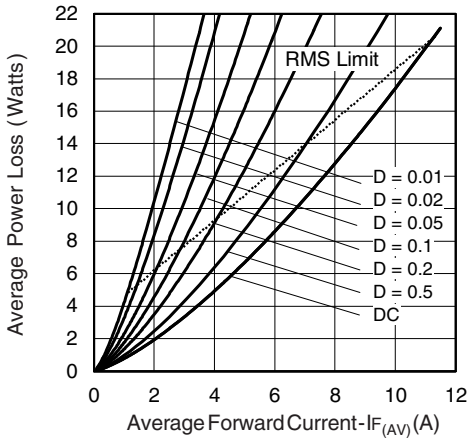


Fig. 6 - Forward Power Loss Characteristics

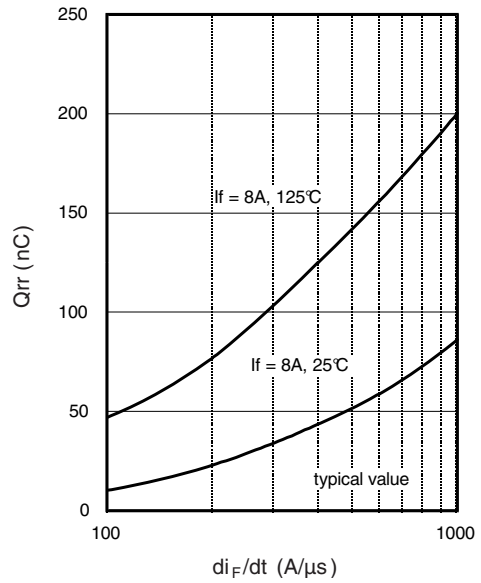
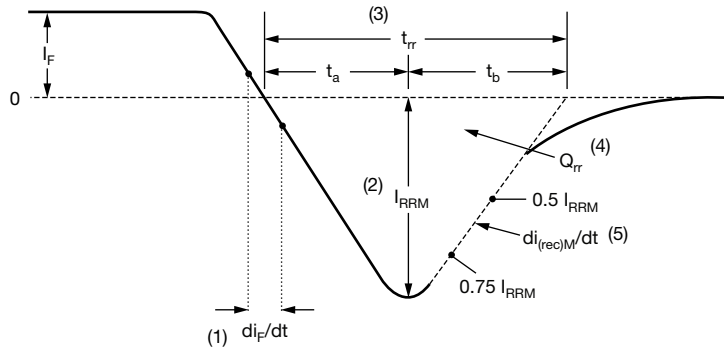


Fig. 8 - Typical Stored Charge vs. di_F/dt



- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	E	T	X	08	06	-M3
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - Circuit configuration:
E = single
- 3** - T = TO-220AC 2L
- 4** - X = hyperfast recovery time
- 5** - Current code: 08 = 8 A
- 6** - Voltage code: 06 = 600 V
- 7** - Environmental digit:
-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

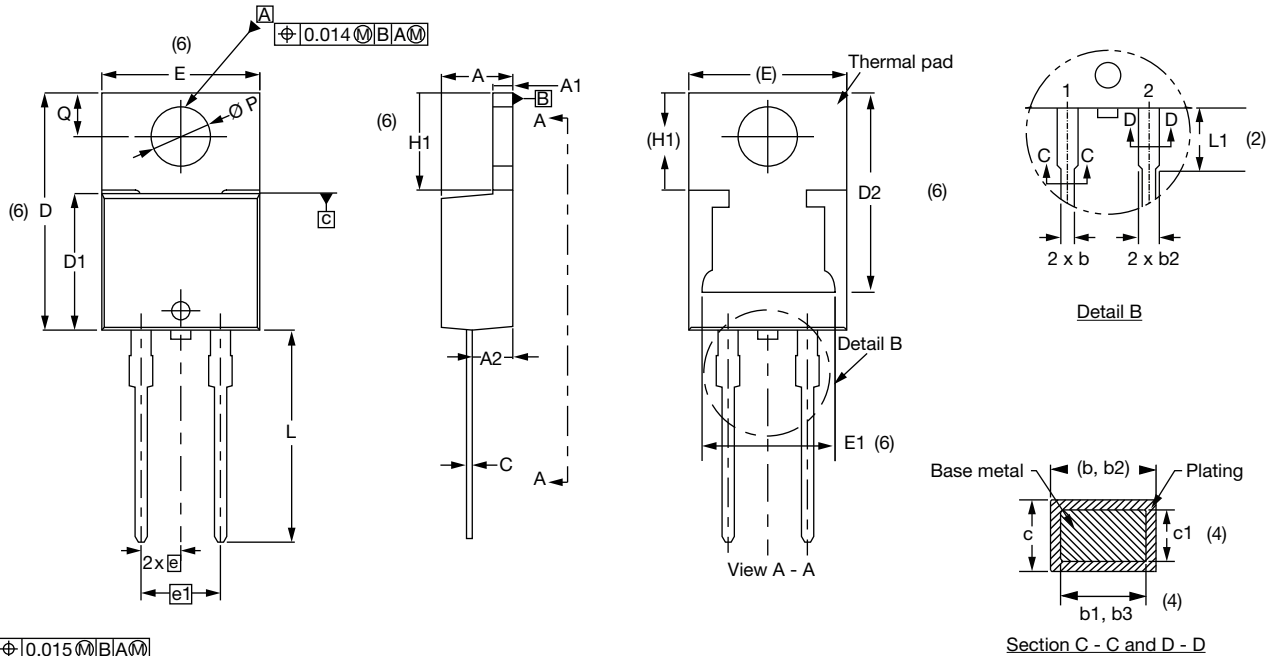
ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-ETX0806-M3	50	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96156
Part marking information	www.vishay.com/doc?95391



TO-220AC 2L

DIMENSIONS in millimeters and inches



Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.50	2.92	0.098	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.35	0.585	0.604	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	13.30	0.460	0.524	6, 7
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
e	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
Ø P	3.54	3.91	0.139	0.154	
Q	2.60	3.00	0.102	0.118	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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